

Reverse Voltage – 50 to 1000 V , Forward Current – 2A

FEATURES

- For surface mounted applications
- Low profile package
- Glass Passivated Chip Junction
- Lead free in comply with EU RoHS 2011/65/EU directives
- Plastic package has underwriters laboratory flammability classification 94V-0
- AEC-Q101 qualified

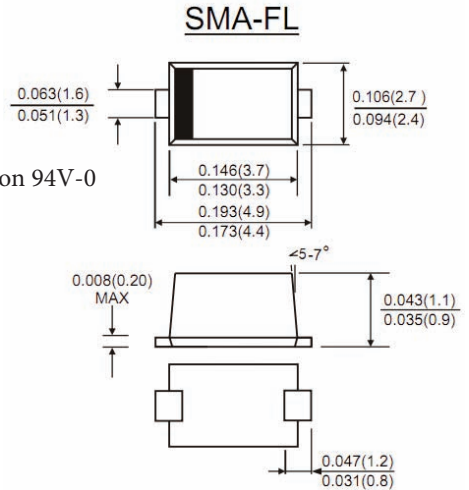
MECHANICAL DATA

- Case: SMA-FL
- Terminals: Solderable per MIL-STD-750, Method 2026

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25°C ambient temperature unless otherwise specified.

Single phase half-wave 60 Hz, resistive or inductive load, for capacitive load current derate by 20 %.



Parameter	Symbols	S2AF	S2BF	S2DF	S2GF	S2JF	S2KF	S2MF	Units
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS voltage	V_{RMS}	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V_{DC}	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current at $T_a = 65^\circ\text{C}$	$I_{F(AV)}$	2.0							A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load (JEDEC Method)	I_{FSM}	50							A
Maximum Instantaneous Forward Voltage at 2A	V_F	1.1							V
Maximum DC Reverse Current at Rated DC Blocking Voltage $T_a = 25^\circ\text{C}$ $T_a = 125^\circ\text{C}$	I_R	5 50							μA
Typical Junction Capacitance ¹⁾	C_j	10							pF
Typical Thermal Resistance ²⁾	$R_{\theta JA}$	80							$^\circ\text{C/W}$
Operating and Storage Temperature Range	T_j, T_{stg}	-55 ~ +150							$^\circ\text{C}$

1) Measured at 1 MHz and applied reverse voltage of 4 V D.C

2) Thermal resistance from junction to ambient at 0.375" (9.5 mm) lead length, P.C.B. mounted



S2AF ~ S2MF

FIG. 1 – TYPICAL FORWARD CURRENT DERATING CURVE

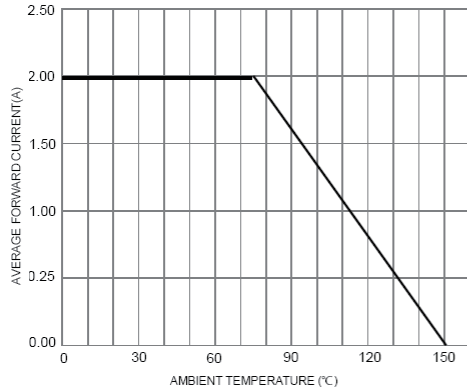


FIG. 2 – TYPICAL FORWARD CHARACTERISTICS

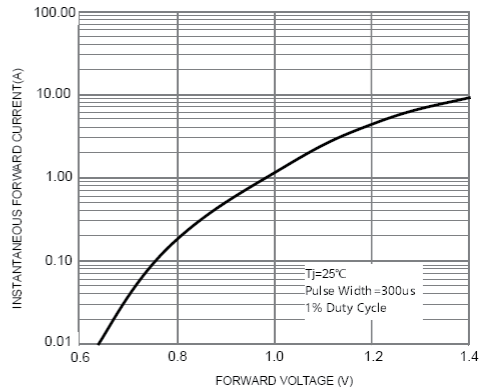


FIG. 3 – MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

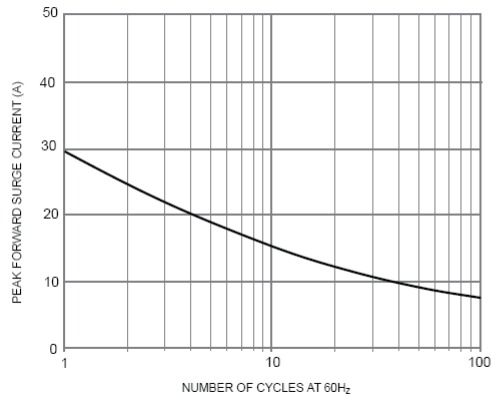


FIG. 4 – TYPICAL REVERSE CHARACTERISTICS

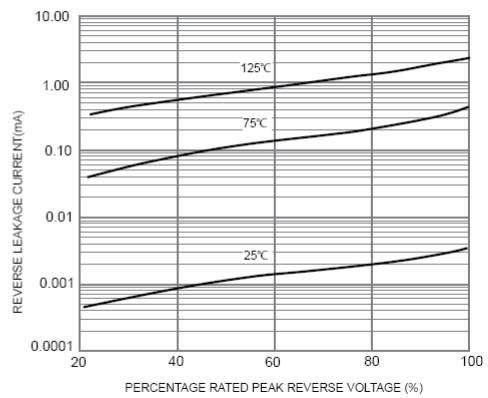


FIG. 5 – TYPICAL JUNCTION CAPACITANCE

